Renesas Electronics America Inc - R7FS5D97E3A01CFC#AA0 Datasheet

Welcome to E-XFL.COM

What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	ARM® Cortex®-M4
Core Size	32-Bit Single-Core
Speed	120MHz
Connectivity	CANbus, EBI/EMI, Ethernet, I²C, IrDA, MMC/SD, QSPI, SCI, SPI, SSI, UART/USART, USB
Peripherals	DMA, LVD, POR, PWM, WDT
Number of I/O	133
Program Memory Size	2MB (2M x 8)
Program Memory Type	FLASH
EEPROM Size	64K x 8
RAM Size	640K x 8
Voltage - Supply (Vcc/Vdd)	2.7V ~ 3.6V
Data Converters	A/D 24x12b; D/A 2x12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 105°C (TA)
Mounting Type	Surface Mount
Package / Case	176-LQFP
Supplier Device Package	176-LFQFP (24x24)
Purchase URL	https://www.e-xfl.com/product-detail/renesas-electronics-america/r7fs5d97e3a01cfc-aa0

Table 1.13 Security

Feature	Functional description
Secure Crypto Engine 7 (SCE7)	• Security algorithms: - Symmetric algorithms: AES, 3DES, and ARC4 - Asymmetric algorithms: RSA and DSA. • Other support features: - TRNG (True Random Number Generator) - Hash-value generation: SHA1, SHA224, SHA256, GHASH - 128-bit unique ID.

1.2 Block Diagram

Figure 1.1 shows the block diagram of the MCU superset. Some individual devices within the group have a subset of the features.

Table 1.16 Pin functions (3 of 5)

Function	Signal	I/O	Description
SPI	RSPCKA, RSPCKB	I/O	Clock input/output pin.
	MOSIA, MOSIB	I/O	Input or output pins for data output from the master.
	MISOA, MISOB	I/O	Input or output pins for data output from the slave.
	SSLA0, SSLB0	I/O	Input or output pin for slave selection.
	SSLA1 to SSLA3, SSLB1 to SSLB3	Output	Output pins for slave selection.
QSPI	QSPCLK	Output	QSPI clock output pin.
	QSSL	Output	QSPI slave output pin.
	QIO0 to QIO3	I/O	Data0 to Data3.
CAN	CRX0, CRX1	Input	Receive data.
	CTX0, CTX1	Output	Transmit data.
USBFS	VCC_USB	Input	Power supply pins.
	VSS_USB	Input	Ground pins.
	USB_DP	I/O	D+ I/O pin of the USB on-chip transceiver. Connect this pin to the D+ pin of the USB bus.
	USB_DM	I/O	D- I/O pin of the USB on-chip transceiver. Connect this pin to the D- pin of the USB bus.
	USB_VBUS	Input	USB cable connection monitor pin. Connect this pin to VBUS of the USB bus. The VBUS pin status (connected or disconnected) can be detected when the USB module is operating as a function controller.
	USB_EXICEN	Output	Low-power control signal for external power supply (OTG) chip.
	USB_VBUSEN	Output	VBUS (5 V) supply enable signal for external power supply chip.
	USB_OVRCURA, USB_OVRCURB	Input	Connect the external overcurrent detection signals to these pins. Connect the VBUS comparator signals to these pins when the OTG power supply chip is connected.
	USB_ID	Input	Connect the MicroAB connector ID input signal to this pin during operation in OTG mode.
USBHS	VCC_USBHS	Input	Power supply pin.
	VSS1_USBHS	Input	Ground pin.
	VSS2_USBHS	Input	Ground pin.
	AVCC_USBHS	Input	Analog power supply pin for the USBHS.
	AVSS_USBHS	Input	Analog ground pin for the USBHS. Must be shorted to the PVSS_USBHS pin.
	PVSS_USBHS	Input	PLL circuit ground pin for the USBHS. Must be shorted to the AVSS_USBHS pin.
	USBHS_RREF	I/O	USBHS reference current source pin. Connect this pin to the AVSS_USBHS pin through a 2.2-kΩ resistor (±1%).
	USBHS_DP	I/O	USB bus D+ data pin.
	USBHS_DM	I/O	USB bus D- data pin.
	USBHS_EXICEN	Output	Connect this pin to the OTG power supply IC.
	USBHS_ID	Input	Connect this pin to the OTG power supply IC.
	USBHS_VBUSEN	Output	VBUS power enable signal for USB.
	USBHS_OVRCURA, USBHS_OVRCURB	Input	Overcurrent pin for USB.
	USBHS_VBUS	Input	USB cable connection monitor input pin.

Table 1.16 Pin functions (4 of 5)

Function	Signal	I/O	Description
ETHERC	REF50CK0	Input	50-MHz reference clock. This pin inputs reference signal for transmission/reception timing in RMII mode.
	RMII0_CRS_DV	Input	Indicates carrier detection signals and valid receive data on RMII0_RXD1 and RMII0_RXD0 in RMII mode.
	RMII0_TXD0, RMII0_TXD1	Output	2-bit transmit data in RMII mode.
	RMII0_RXD0, RMII0_RXD1	Input	2-bit receive data in RMII mode.
	RMII0_TXD_EN	Output	Output pin for data transmit enable signal in RMII mode.
	RMII0_RX_ER	Input	Indicates an error occurred during reception of data in RMII mode.
	ET0_CRS	Input	Carrier detection/data reception enable signal.
	ET0_RX_DV	Input	Indicates valid receive data on ET0_ERXD3 to ET0_ERXD0.
	ET0_EXOUT	Output	General-purpose external output pin.
	ET0_LINKSTA	Input	Input link status from the PHY-LSI.
	ET0_ETXD0 to ET0_ETXD3	Output	4 bits of MII transmit data.
	ET0_ERXD0 to ET0_ERXD3	Input	4 bits of MII receive data.
	ET0_TX_EN	Output	Transmit enable signal. Functions as signal indicating that transmit data is ready on ET_ETXD3 to ET_ETXD0.
	ET0_TX_ER	Output	Transmit error pin. Functions as signal notifying the PHY_LSI of an error during transmission.
	ET0_RX_ER	Input	Receive error pin. Functions as signal to recognize an error during reception.
	ET0_TX_CLK	Input	Transmit clock pin. This pin inputs reference signal for output timing from ET0_TX_EN, ET0_ETXD3 to ET0_ETXD0, and ET0_TX_ER.
	ET0_RX_CLK	Input	Receive clock pin. This pin inputs reference signal for input timing to ET0_RX_DV, ET0_ERXD3 to ET0_ERXD0, and ET0_RX_ER.
	ET0_COL	Input	Input collision detection signal.
	ET0_WOL	Output	Receive Magic packets.
	ET0_MDC	Output	Output reference clock signal for information transfer through ET0_MDIO.
	ET0_MDIO	I/O	Input or output bidirectional signal for exchange of management data with PHY-LSI.
SDHI	SD0CLK, SD1CLK	Output	SD clock output pins.
	SD0CMD, SD1CMD	I/O	Command output pin and response input signal pins.
	SD0DAT0 to SD0DAT7, SD1DAT0 to SD1DAT7	I/O	SD and MMC data bus pins.
	SD0CD, SD1CD	Input	SD card detection pins.
	SD0WP, SD1WP	Input	SD write-protect signals.
Analog power supply	AVCC0	Input	Analog voltage supply pin. This is used as the analog power supply for the respective modules. Supply this pin with the same voltage as the VCC pin.
	AVSS0	Input	Analog ground pin. This is used as the analog ground for the respective modules. Supply this pin with the same voltage as the VSS pin.
	VREFH0	Input	Analog reference voltage supply pin for the ADC12 (unit 0). Connect this pin to VCC when not using the ADC12 (unit 0) and sample-and-hold circuit for AN000 to AN002.
	VREFL0	Input	Analog reference ground pin for the ADC12. Connect this pin to VSS when not using the ADC12 (unit 0) and sample-and-hold circuit for AN000 to AN002.
	VREFH	Input	Analog reference voltage supply pin for the ADC12 (unit 1) and D/A Converter. Connect this pin to VCC when not using the ADC12 (unit 1), sample-and-hold circuit for AN100 to AN102, and D/A Converter.
	VREFL	Input	Analog reference ground pin for the ADC12 and D/A Converter. Connect this pin to VSS when not using the ADC12 (unit 1), sample-and-hold circuit for AN100 to AN102, and D/A Converter.

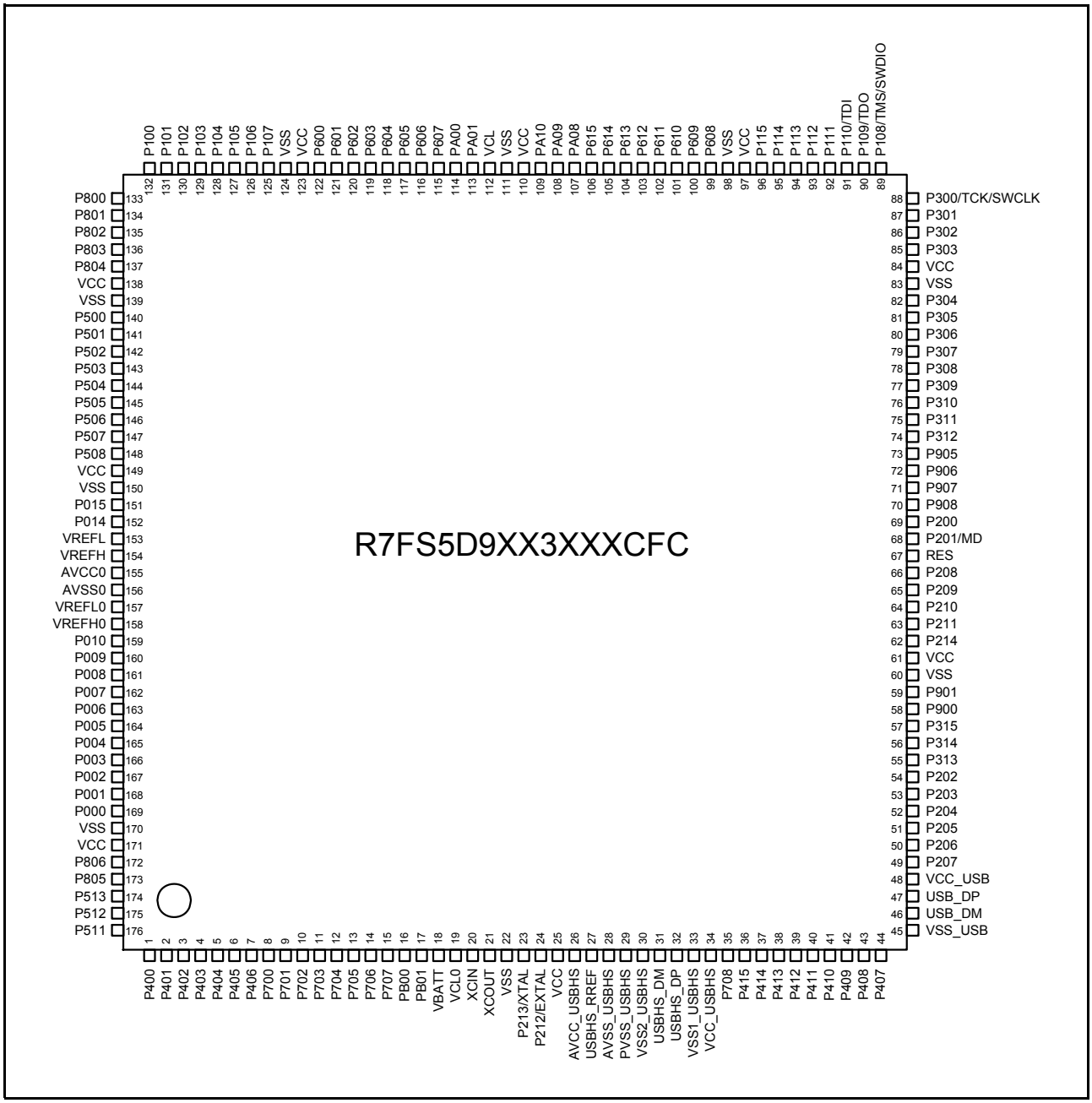


Figure 1.4 Pin assignment for 176-pin LQFP (top view)

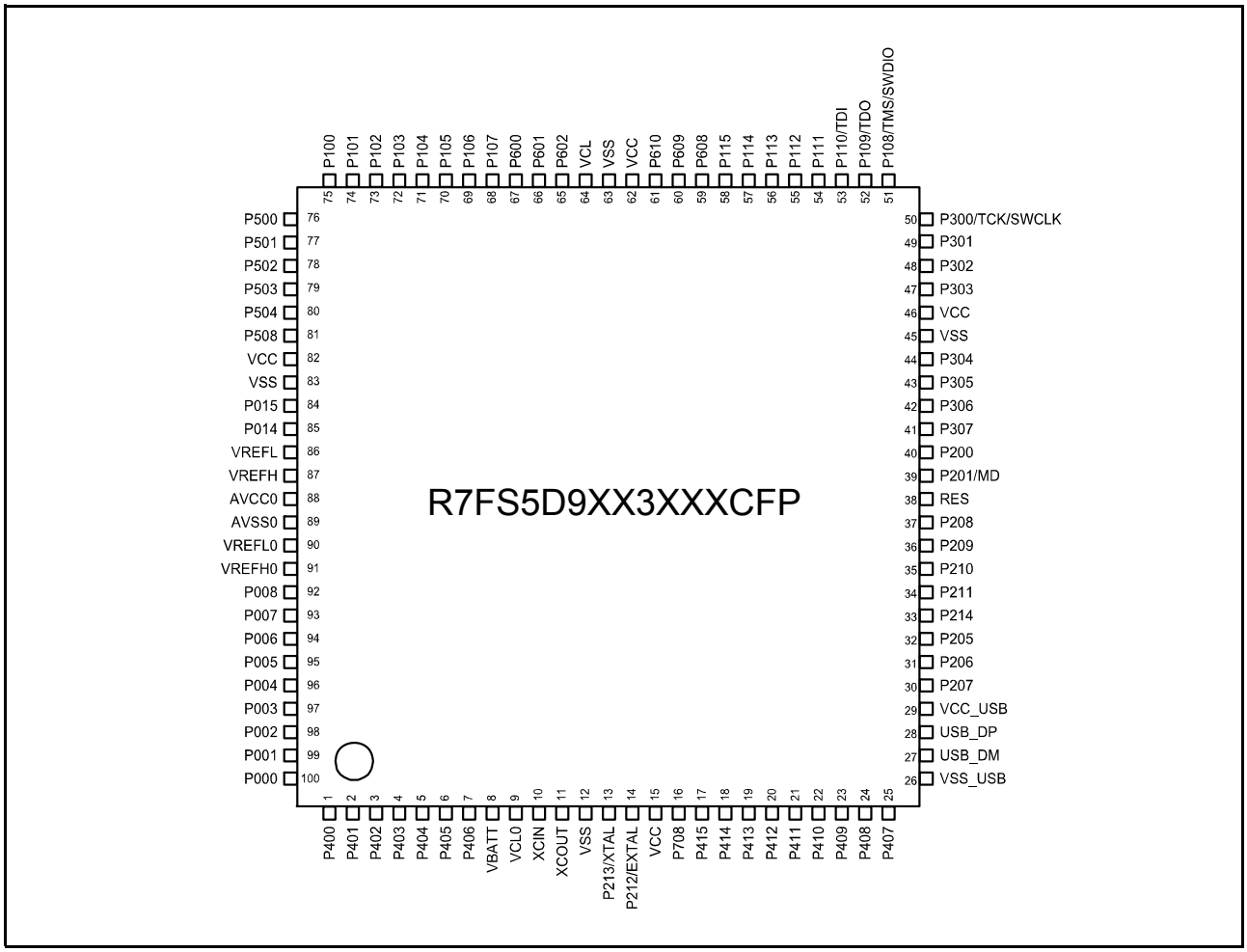


Figure 1.7 Pin assignment for 100-pin LQFP (top view)

Pin number					Power, System, Clock, Debug, CAC	Interrupt	I/O port	Extbus		Timers				Communication interfaces											Analog		HMI	
BGA176	LQFP176	LGA145	LQFP144	LQFP100				External bus	SDRAM	AGT	GPT	GPT	RTC	USBFS, CAN	SCI0,2,4,6,8 (30 MHz)	SCI1,3,5,7,9 (30 MHz)	IIC	SPI, QSPI	SSIE	ETHERC (MII) (25 MHz)	ETHERC (RMII) (50 MHz)	USBHS	SDHI	ADC12	DAC12, ACMPHS	CTSU	GLCDC, PDC
G4	108	-	-	-	-	-	PA09	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	LCD_DATA08_B
G2	109	-	-	-	-	-	PA10	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	LCD_DATA07_B
G3	110	G1	90	62	VCC	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-
H3	111	G2	91	63	VSS	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-
H1	112	H1	92	64	VCL	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-
H2	113	-	-	-	-	-	PA01	-	-	-	-	-	-	-	SCK8	-	-	-	-	-	-	-	-	-	-	-	LCD_DATA06_B
H4	114	-	-	-	-	-	PA00	-	-	-	-	-	-	-	TXD8	-	-	-	-	-	-	-	-	-	-	-	LCD_DATA05_B
J4	115	-	-	-	-	-	P607	-	-	-	-	-	-	-	RXD8	-	-	-	-	-	-	-	-	-	-	-	LCD_DATA04_B
J1	116	-	-	-	-	-	P606	-	-	-	-	-	RTCOUT	-	CTS8_RTS8/SS8	-	-	-	-	-	-	-	-	-	-	-	LCD_DATA03_B
J2	117	H2	93	-	-	-	P605	D11[A11/D11]	DQ11	-	-	GTIOC8A	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-
J3	118	G4	94	-	-	-	P604	D12[A12/D12]	DQ12	-	-	GTIOC8B	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-
K3	119	H3	95	-	-	-	P603	D13[A13/D13]	DQ13	-	-	GTIOC7A	-	-	-	CTS9_RTS9/SS9	-	-	-	-	-	-	-	-	-	-	-
K1	120	J1	96	65	-	-	P602	EBCLK	SDCLK	-	-	GTIOC7B	-	-	-	TXD9	-	-	-	-	-	-	-	-	-	-	LCD_DATA04_A
K2	121	J2	97	66	-	-	P601	WR/WR0	DQM0	-	-	GTIOC6A	-	-	-	RXD9	-	-	-	-	-	-	-	-	-	-	LCD_DATA03_A
L1	122	H4	98	67	CLKOUT/CACREF	-	P600	RD	-	-	-	GTIOC6B	-	-	-	SCK9	-	-	-	-	-	-	-	-	-	-	LCD_DATA02_A
K4	123	K2	99	-	VCC	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-
L4	124	K1	100	-	VSS	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-
L2	125	J3	101	68	-	KR07	P107	D07[A07/D07]	DQ07	AGTOA0	-	GTIOC8A	-	-	CTS8_RTS8/SS8	-	-	-	-	-	-	-	-	-	-	LCD_DATA01_A
M1	126	K3	102	69	-	KR06	P106	D06[A06/D06]	DQ06	AGTOB0	-	GTIOC8B	-	-	SCK8	-	-	SSLA3_A	-	-	-	-	-	-	-	-	LCD_DATA00_A
L3	127	J4	103	70	-	IRQ0/KR05	P105	D05[A05/D05]	DQ05	-	GTETRGA	GTIOC1A	-	-	TXD8/MOSI8/SDA8	-	-	SSLA2_A	-	-	-	-	-	-	-	-	LCD_TCON3_A
M2	128	L3	104	71	-	IRQ1/KR04	P104	D04[A04/D04]	DQ04	-	GTETRGB	GTIOC1B	-	-	RXD8/MISO8/SCL8	-	-	SSLA1_A	-	-	-	-	-	-	-	-	LCD_TCON2_A
N1	129	L1	105	72	-	KR03	P103	D03[A03/D03]	DQ03	-	GTOWUP	GTIOC2A_A	-	CTX0	CTS0_RTS0/SS0	-	-	SSLA0_A	-	-	-	-	-	-	-	-	LCD_TCON1_A
M3	130	M1	106	73	-	KR02	P102	D02[A02/D02]	DQ02	AGTO0	GTOWLO	GTIOC2B_A	-	CRX0	SCK0	-	-	RSPCKA_A	-	-	-	-	-	ADTRG0	-	-	LCD_TCON0_A
N2	131	M2	107	74	-	IRQ1/KR01	P101	D01[A01/D01]	DQ01	AGTEE0	GTETRGB	GTIOC5A	-	-	TXD0/MOSI0/SDA0	CTS1_RTS1/SS1	SDA1_B	MOSIA_A	-	-	-	-	-	-	-	-	LCD_CLK_A
P1	132	N1	108	75	-	IRQ2/KR00	P100	D00[A00/D00]	DQ00	AGTIO0	GTETRGA	GTIOC5B	-	-	RXD0/MISO0/SCL0	SCK1	SCL1_B	MISOA_A	-	-	-	-	-	-	-	-	LCD_EXTCLK_A
N3	133	L2	109	-	-	-	P800	D14[A14/D14]	DQ14	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-
R1	134	N2	110	-	-	-	P801	D15[A15/D15]	DQ15	-	-	-	-	-	-	-	-	-	-	-	-	-	SD1DAT4_A	-	-	-	-
P2	135	-	-	-	-	-	P802	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	SD1DAT5_A	-	-	-	LCD_DATA02_B
R2	136	-	-	-	-	-	P803	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	SD1DAT6_A	-	-	-	LCD_DATA01_B
P3	137	-	-	-		-	P804	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	SD1DAT7_A	-	-	-	LCD_DATA00_B
N4	138	N3	111	-	VCC	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-
M4	139	M3	112	-	VSS	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-
R3	140	K4	113	76	-	-	P500	-	-	AGTOA0	GTIU	GTIOC11A	-	USB_VBUSEN	-	-	-	QSPCLK	-	-	-	-	SD1CLK_A	AN016	IVREF0	-	-
P4	141	M4	114	77	-	IRQ11	P501	-	-	AGTOB0	GTIV	GTIOC11B	-	USB_OVRCURA	-	TXD5/MOSI5/SDA5	-	QSSL	-	-	-	-	SD1CMD_A	AN116	IVREF1	-	-
R4	142	L4	115	78	-	IRQ12	P502	-	-	-	GTIW	GTIOC12A	-	USB_OVRCURB	-	RXD5/MISO5/SCL5	-	QIO0	-	-	-	-	SD1DAT0_A	AN017	IVCMP0	-	-
N5	143	K5	116	79	-	-	P503	-	-	-	GTETRGC	GTIOC12B	-	USB_EXICEN	CTS6_RTS6/SS6	SCK5	-	QIO1	-	-	-	-	SD1DAT1_A	AN117	-	-	-
P5	144	L5	117	80	-	-	P504	ALE	-	-	GTETRGD	GTIOC13A	-	USB_ID	SCK6	CTS5_RTS5/SS5	-	QIO2	-	-	-	-	SD1DAT2_A	AN018	-	-	-
P6	145	K6	118	-	-	IRQ14	P505	-	-	-	-	GTIOC13B	-	-	RXD6/MISO6/SCL6	-	-	QIO3	-	-	-	-	SD1DAT3_A	AN118	-	-	-

2.2.2 I/O V_{IH}, V_{IL}

Table 2.4 I/O V_{IH}, V_{IL}

Item					Symbol	Min	Typ	Max	Unit
Input voltage (except for Schmitt trigger input pins)	Peripheral function pin	EXTAL(external clock input), WAIT, SPI (except RSPCK)			V_{IH}	VCC × 0.8	-	-	V
					V_{IL}	-	-	VCC × 0.2	
		D00 to D15, DQ00 to DQ15			V_{IH}	VCC × 0.7	-	-	
					V_{IL}	-	-	VCC × 0.3	
		ETHERC			V_{IH}	2.3	-	-	
					V_{IL}	-	-	VCC × 0.2	
		IIC (SMBus)*1			V_{IH}	2.1	-	-	
					V_{IL}	-	-	0.8	
		IIC (SMBus)*2			V_{IH}	2.1	-	VCC + 3.6 (max 5.8)	
					V_{IL}	-	-	0.8	
Schmitt trigger input voltage		IIC (except for SMBus)*1			V_{IH}	VCC × 0.7	-	-	
					V_{IL}	-	-	VCC × 0.3	
					ΔV_T	VCC × 0.05	-	-	
		IIC (except for SMBus)*2			V_{IH}	VCC × 0.7	-	VCC + 3.6 (max 5.8)	
					V_{IL}	-	-	VCC × 0.3	
					ΔV_T	VCC × 0.05	-	-	
		5V-tolerant ports*3, *7			V_{IH}	VCC × 0.8	-	VCC + 3.6 (max 5.8)	
					V_{IL}	-	-	VCC × 0.2	
					ΔV_T	VCC × 0.05	-	-	
		RTCIC0, RTCIC1, RTCIC2	When using the Battery Backup Function	When VBATT power supply is selected	V_{IH}	V_{BATT} × 0.8	-	V_{BATT} + 0.3	
					V_{IL}	-	-	V_{BATT} × 0.2	
					ΔV_T	V_{BATT} × 0.05	-	-	
				When VCC power supply is selected	V_{IH}	VCC × 0.8	-	Higher voltage either VCC + 0.3 V or V_{BATT} + 0.3 V	
					V_{IL}	-	-	VCC × 0.2	
					ΔV_T	VCC × 0.05	-	-	
			When not using the Battery Backup Function		V_{IH}	VCC × 0.8	-	VCC + 0.3	
					V_{IL}	-	-	VCC × 0.2	
					ΔV_T	VCC × 0.05	-	-	
		Other input pins*4			V_{IH}	VCC × 0.8	-	-	
					V_{IL}	-	-	VCC × 0.2	
					ΔV_T	VCC × 0.05	-	-	
	Ports	5V-tolerant ports*5, *7			V_{IH}	VCC × 0.8	-	VCC + 3.6 (max 5.8)	
					V_{IL}	-	-	VCC × 0.2	
		Other input pins*6			V_{IH}	VCC × 0.8	-	-	
					V_{IL}	-	-	VCC × 0.2	

Note 1. SCL0_B (P204), SCL1_B, SDA1_B (total 3 pins).
Note 2. SCL0_A, SDA0_A, SCL0_B (P408), SDA0_B, SCL1_A, SDA1_A, SCL2, SDA2 (total 8 pins).
Note 3. RES and peripheral function pins associated with P205, P206, P400, P401, P407 to P415, P511, P512, P708 to P713, PB01 (total 23 pins).

Table 2.7 Operating and standby current (2 of 2)

Item			Symbol	Min	Typ	Max	Unit	Test conditions
USB operating current	Low speed	USB	$I_{CCUSBLS}$	-	3.5	6.5	mA	VCC_USB
		USBHS		-	10.5	13.5	mA	VCC_USBHS = AVCC_USBHS (PHYSET.HSEB = 0)
		USBHS		-	2.8	3.6	mA	VCC_USBHS = AVCC_USBHS (PHYSET.HSEB = 1)
	Full speed	USB	$I_{CCUSBFS}$	-	4.0	10.0	mA	VCC_USB
		USBHS		-	14	22	mA	VCC_USBHS = AVCC_USBHS (PHYSET.HSEB = 0)
		USBHS		-	6.5	13.0	mA	VCC_USBHS = AVCC_USBHS (PHYSET.HSEB = 1)
	High speed	USBHS	$I_{CCUSBHS}$	-	50	65	mA	VCC_USBHS = AVCC_USBHS
	Standby mode (direct power down)	USBHS	$I_{CCUSBSBY}$	-	0.5	4.5	µA	VCC_USBHS = AVCC_USBHS

Note 1. Supply current values are with all output pins unloaded and all input pull-up MOS transistors in the off state.
Note 2. Measured with clocks supplied to the peripheral functions. This does not include the BGO operation.
Note 3. ICC depends on f (ICLK) as follows. (ICLK:PCLKA:PCLKB:PCLKC:PCLKD:BCK:EBCLK = 2:2:1:1:2:1:1)
ICC Max. = 0.84 × f + 37 (max. operation in High-speed mode)
ICC Typ. = 0.09 × f + 3.7 (normal operation in High-speed mode)
ICC Typ. = 0.6 × f + 1.8 (Low-speed mode 1)
ICC Max. = 0.08 × f + 37 (Sleep mode).
Note 4. This does not include the BGO operation.
Note 5. Supply of the clock signal to peripherals is stopped in this state. This does not include the BGO operation.
Note 6. FCLK, BCLK, PCLKA, PCLKB, PCLKC, and PCLKD are set to divided by 64 (3.75 MHz).
Note 7. When using ETHERC, GLCDC, DRW, and JPEG, PCLKA frequency is such that PCLKA = ICLK.
Note 8. When the MCU is in Software Standby mode or the MSTPCRD.MSTPD16 (ADC120 module stop bit) and MSTPCRD.MSTPD15 (ADC121 module stop bit) are in the module stop state.

Note 1. The recovery time is determined by the system clock source. When multiple oscillators are active, the recovery time can be determined with the following equation:
Total recovery time = recovery time for an oscillator as the system clock source + the longest oscillation stabilization time of any oscillators requiring longer stabilization times than the system clock source + 2 LOCO cycles (when LOCO is operating) + 3 SOSC cycles (when Subosc is oscillating and MSTPC0 = 0 (CAC module stop)).

Note 2. When the frequency of the crystal is 24 MHz (Main Clock Oscillator Wait Control Register (MOSCWTCR) is set to 05h). For other settings (MOSCWTCR is set to Xh), the recovery time can be determined with the following equation:
t_{SBYMC} (MOSCWTCR = Xh) = t_{SBYMC} (MOSCWTCR = 05h) + ($t_{MAINOSCWT}$ (MOSCWTCR = Xh) - $t_{MAINOSCWT}$ (MOSCWTCR = 05h))

Note 3. When the frequency of PLL is 240 MHz (Main Clock Oscillator Wait Control Register (MOSCWTCR) is set to 05h). For other settings (MOSCWTCR is set to Xh), the recovery time can be determined with the following equation:
t_{SBYMC} (MOSCWTCR = Xh) = t_{SBYMC} (MOSCWTCR = 05h) + ($t_{MAINOSCWT}$ (MOSCWTCR = Xh) - $t_{MAINOSCWT}$ (MOSCWTCR = 05h))

Note 4. When the frequency of the external clock is 24 MHz (Main Clock Oscillator Wait Control Register (MOSCWTCR) is set to 00h). For other settings (MOSCWTCR is set to Xh), the recovery time can be determined with the following equation:
t_{SBYMC} (MOSCWTCR = Xh) = t_{SBYMC} (MOSCWTCR = 00h) + ($t_{MAINOSCWT}$ (MOSCWTCR = Xh) - $t_{MAINOSCWT}$ (MOSCWTCR = 00h))

Note 5. When the frequency of PLL is 240 MHz (Main Clock Oscillator Wait Control Register (MOSCWTCR) is set to 00h). For other settings (MOSCWTCR is set to Xh), the recovery time can be determined with the following equation:
t_{SBYMC} (MOSCWTCR = Xh) = t_{SBYMC} (MOSCWTCR = 00h) + ($t_{MAINOSCWT}$ (MOSCWTCR = Xh) - $t_{MAINOSCWT}$ (MOSCWTCR = 00h))

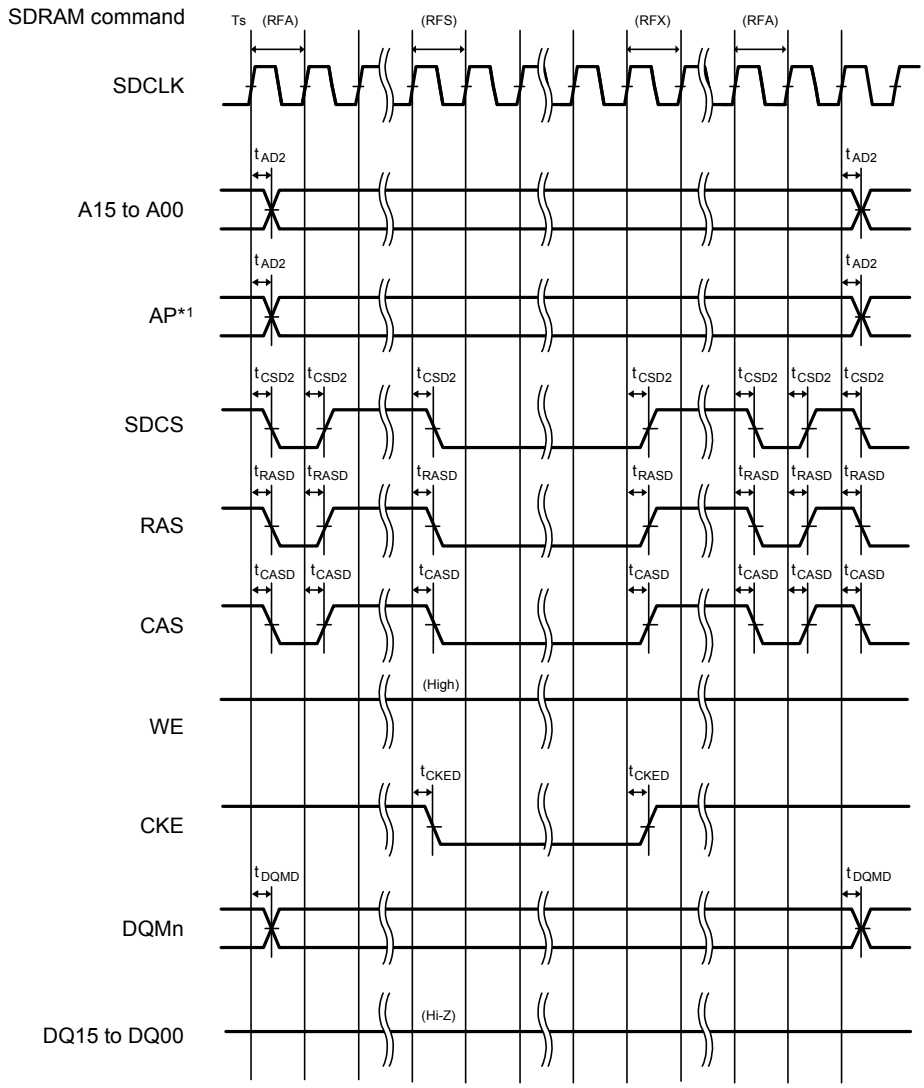
Note 6. The HOCO frequency is 20 MHz.

Note 7. The MOCO frequency is 8 MHz.

Note 8. In Subosc-speed mode, the sub-clock oscillator or LOCO continues oscillating in Software Standby mode.

Note 9. When the SNZCR.RXDREQEN bit is set to 0, the following time is added as the power supply recovery time:
STCONR.STCON[1:0] = 00b:16 µs (typical), 34 µs (maximum)
STCONR.STCON[1:0] = 11b:16 µs (typical), 104 µs (maximum).

Note 10. When the SNZCR.RXDREQEN bit is set to 0, 16 µs (typical) or 18 µs (maximum) is added as the HOCO wait time.



Note 1. Address pins are for output of the precharge-select command (Precharge-sel) for the SDRAM.

Figure 2.29 SDRAM self-refresh timing

2.3.7 I/O Ports, POEG, GPT32, AGT, KINT, and ADC12 Trigger Timing

Table 2.19 I/O ports, POEG, GPT32, AGT, KINT, and ADC12 trigger timing (1 of 2)

GPT32 Conditions:
High drive output is selected in the port drive capability bit in the PmnPFS register.

AGT Conditions:
Middle drive output is selected in the port drive capability bit in the PmnPFS register.

Item		Symbol	Min	Max	Unit	Test conditions
I/O ports	Input data pulse width	t_{PRW}	1.5	-	t_{Pcyc}	Figure 2.30
POEG	POEG input trigger pulse width	t_{POEW}	3	-	t_{Pcyc}	Figure 2.31

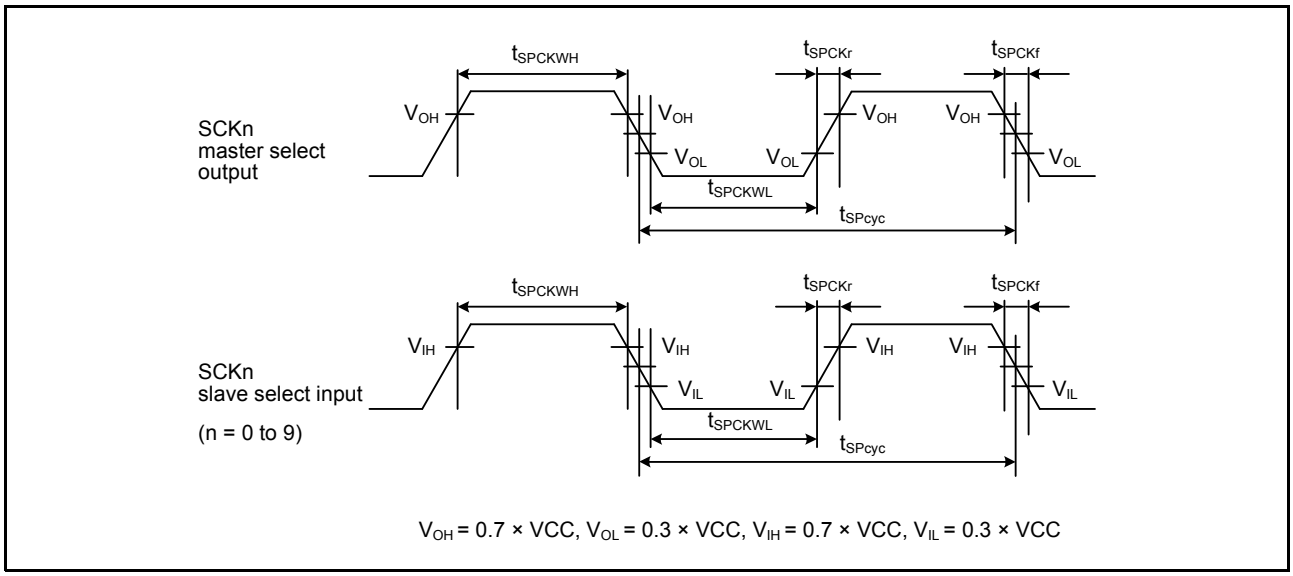


Figure 2.41 SCI simple SPI mode clock timing

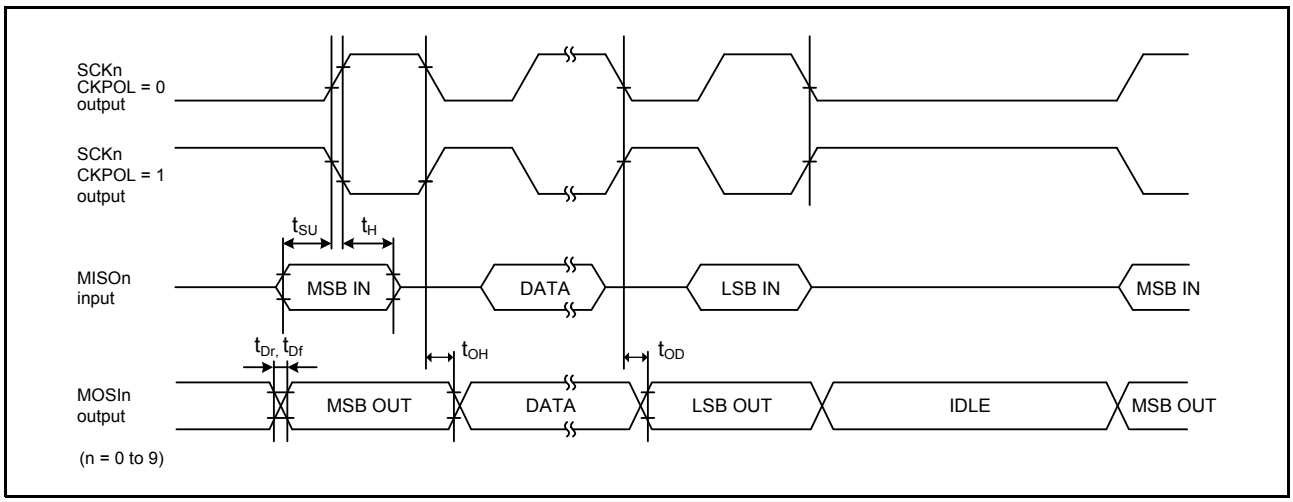


Figure 2.42 SCI simple SPI mode timing for master when CKPH = 1

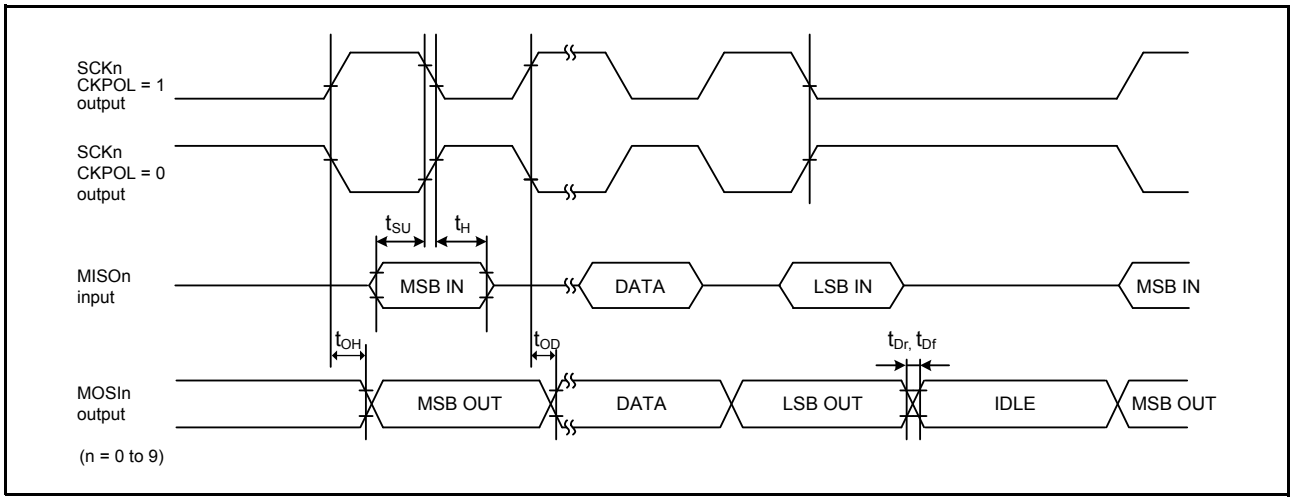


Figure 2.43 SCI simple SPI mode timing for master when CKPH = 0

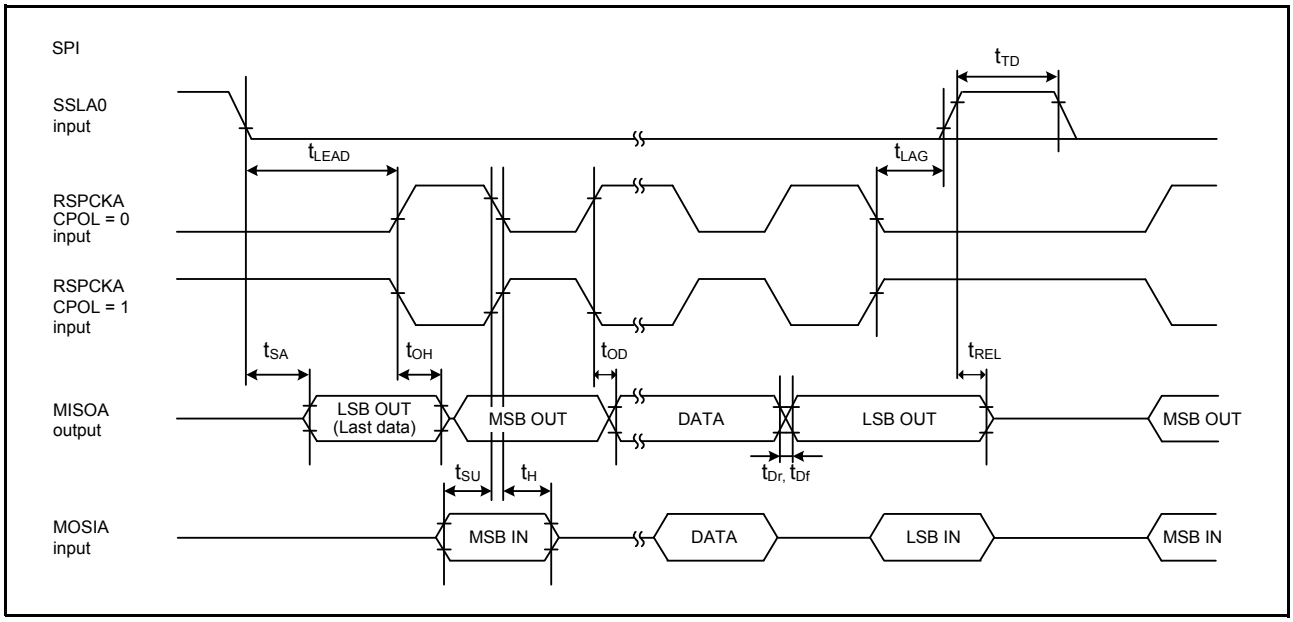


Figure 2.53 SPI timing for slave when CPHA = 1

2.3.12 QSPI Timing

Table 2.26 QSPI timing
Conditions: High drive output is selected in the port drive capability bit in the PmnPFS register.

Item		Symbol	Min	Max	Unit*1	Test conditions
QSPI	QSPCK clock cycle	t_{QScyc}	2	48	t_{Pcyc}	Figure 2.54
	QSPCK clock high pulse width	t_{QSWH}	t_{QScyc} × 0.4	-	ns	
	QSPCK clock low pulse width	t_{QSWL}	t_{QScyc} × 0.4	-	ns	
	Data input setup time	t_{Su}	8	-	ns	Figure 2.55
	Data input hold time	t_{IH}	0	-	ns	
	QSSL setup time	t_{LEAD}	(N+0.5) x t_{Qscyc} - 5 *2	(N+0.5) x t_{Qscyc} +100 *2	ns	
	QSSL hold time	t_{LAG}	(N+0.5) x t_{Qscyc} - 5 *3	(N+0.5) x t_{Qscyc} +100 *3	ns	
	Data output delay	t_{OD}	-	4	ns	
	Data output hold time	t_{OH}	–3.3	-	ns	
	Successive transmission delay	t_{TD}	1	16	t_{QScyc}	

Note 1. t_{Pcyc}: PCLKA cycle.
Note 2. N is set to 0 or 1 in SFMSLD.
Note 3. N is set to 0 or 1 in SFMSHD.

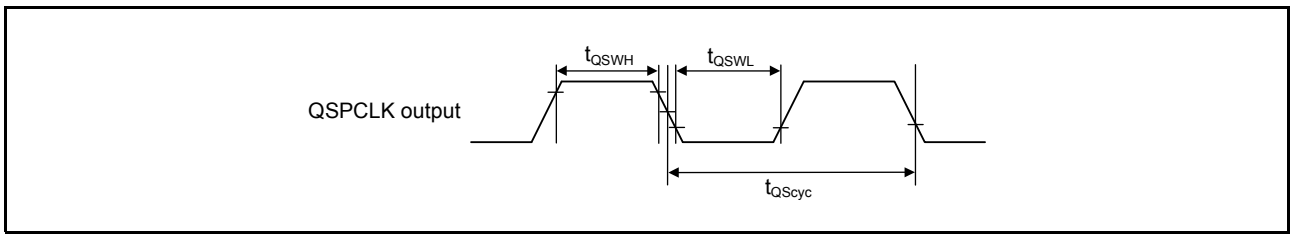


Figure 2.54 QSPI clock timing

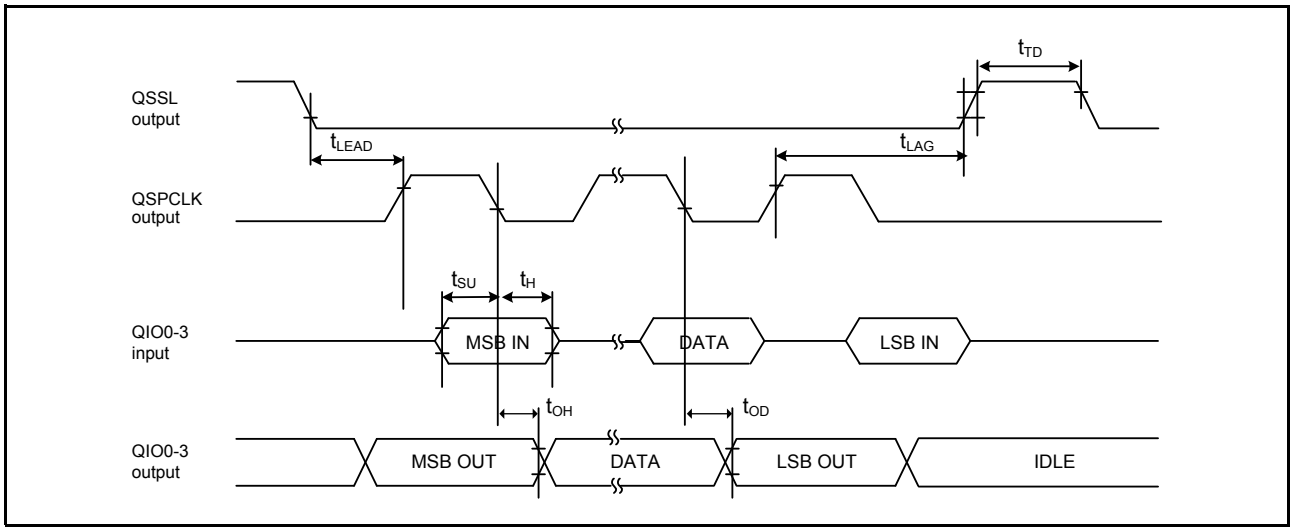


Figure 2.55 Transmit and receive timing

2.3.13 IIC Timing

Table 2.27 IIC timing (1) (1 of 2)

(1) Conditions: Middle drive output is selected in the port drive capability bit in the PmnPFS register for the following pins: SDA0_B, SCL0_B, SDA1_A, SCL1_A, SDA1_B, SCL1_B.

(2) The following pins do not require setting: SCL0_A, SDA0_A, SCL2, SDA2.

(3) Use pins that have a letter appended to their names, for instance "_A" or "_B", to indicate group membership. For the IIC interface, the AC portion of the electrical characteristics is measured for each group.

Item		Symbol	Min*1	Max	Unit	Test conditions*3
IIC (Standard mode, SMBus) ICFER.FMPE = 0	SCL input cycle time	t_{SCL}	6 (12) × t_{IICcyc} + 1300	-	ns	Figure 2.56
	SCL input high pulse width	t_{SCLH}	3 (6) × t_{IICcyc} + 300	-	ns	
	SCL input low pulse width	t_{SCLL}	3 (6) × t_{IICcyc} + 300	-	ns	
	SCL, SDA input rise time	t_{Sr}	-	1000	ns	
	SCL, SDA input fall time	t_{Sf}	-	300	ns	
	SCL, SDA input spike pulse removal time	t_{SP}	0	1 (4) × t_{IICcyc}	ns	
	SDA input bus free time when wakeup function is disabled	t_{BUF}	3 (6) × t_{IICcyc} + 300	-	ns	
	SDA input bus free time when wakeup function is enabled	t_{BUF}	3 (6) × t_{IICcyc} + 4 × t_{Pcyc} + 300	-	ns	
	START condition input hold time when wakeup function is disabled	t_{STAH}	t_{IICcyc} + 300	-	ns	
	START condition input hold time when wakeup function is enabled	t_{STAH}	1 (5) × t_{IICcyc} + t_{Pcyc} + 300	-	ns	
	Repeated START condition input setup time	t_{STAS}	1000	-	ns	
	STOP condition input setup time	t_{STOS}	1000	-	ns	
	Data input setup time	t_{SDAS}	t_{IICcyc} + 50	-	ns	
	Data input hold time	t_{SDAH}	0	-	ns	
	SCL, SDA capacitive load	C_b	-	400	pF	

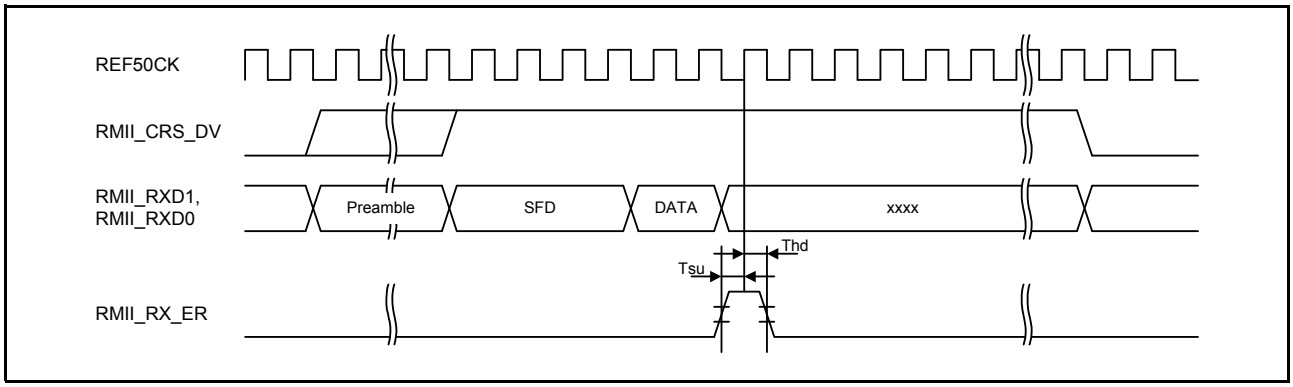


Figure 2.66 RMII reception timing when an error occurs

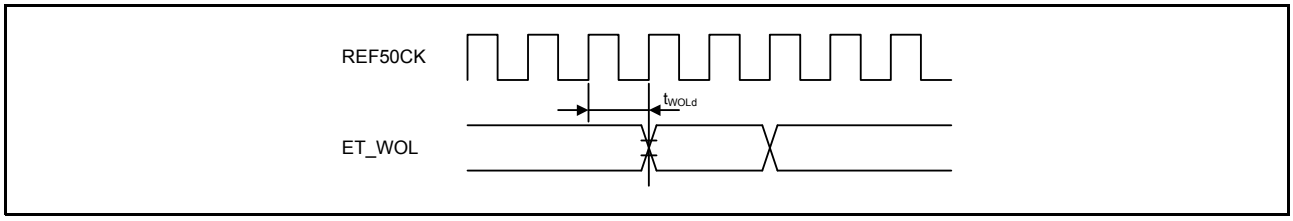


Figure 2.67 WOL output timing for RMII

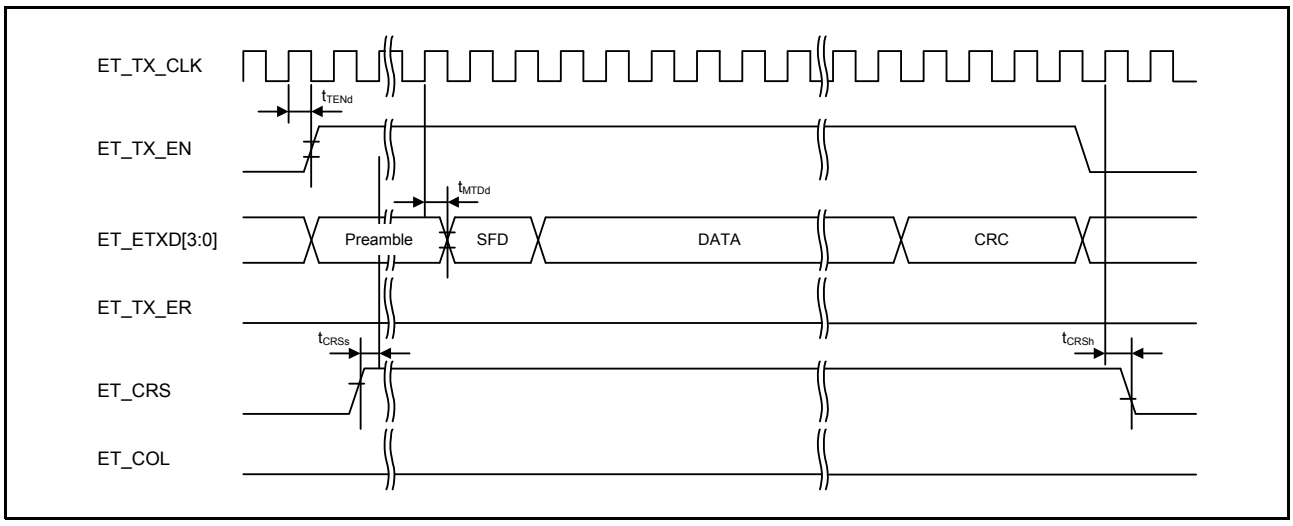


Figure 2.68 MII transmission timing in normal operation

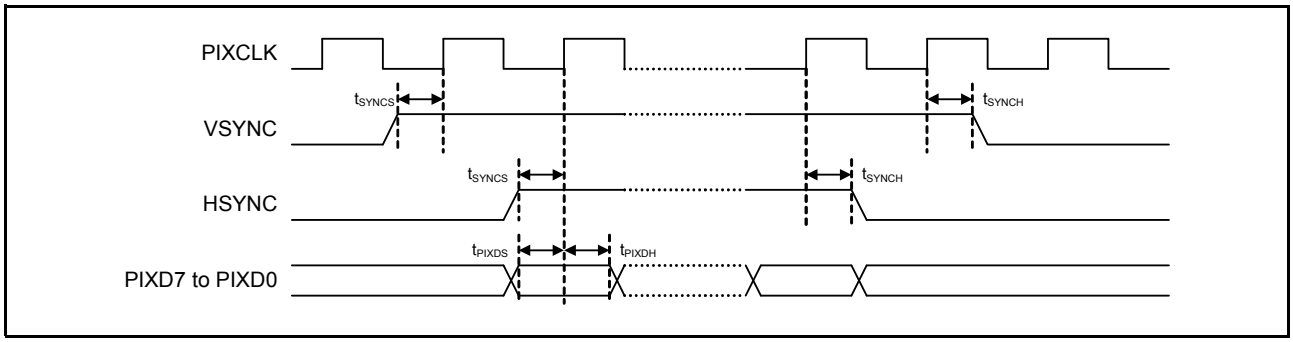


Figure 2.75 PDC AC timing

2.3.18 GLCDC Timing

Table 2.33 GLCDC timing
Conditions:
LCD_CLK: High drive output is selected in the port drive capability bit in the PmnPFS register.
LCD_DATA: Middle drive output is selected in the port drive capability bit in the PmnPFS register.

Item		Symbol	Min	Typ	Max	Unit	Test conditions
LCD_EXTCLK input clock frequency		t_{Ecyc}	-	-	60*1	MHz	Figure 2.76
LCD_EXTCLK input clock low pulse width		t_{WL}	0.45	-	0.55	t_{Ecyc}	
LCD_EXTCLK input clock high pulse width		t_{WH}	0.45	-	0.55		
LCD_CLK output clock frequency		t_{Lcyc}	-	-	60*1	MHz	Figure 2.77
LCD_CLK output clock low pulse width		t_{LOL}	0.4	-	0.6	t_{Lcyc}	Figure 2.77
LCD_CLK output clock high pulse width		t_{LOH}	0.4	-	0.6	t_{Lcyc}	Figure 2.77
LCD data output delay timing	_A or _B combinations*2	t_{DD}	–3.5	-	4	ns	Figure 2.78
	_A and _B combinations*3		–5.0	-	5.5		

Note 1. Parallel RGB888, 666,565: Maximum 54 MHz
Serial RGB888: Maximum 60 MHz (4x speed)
Note 2. Use pins that have a letter appended to their names, for instance, “_A” or “_B”, to indicate
Note 3. Pins of group “_A” and “_B” combinations are used.

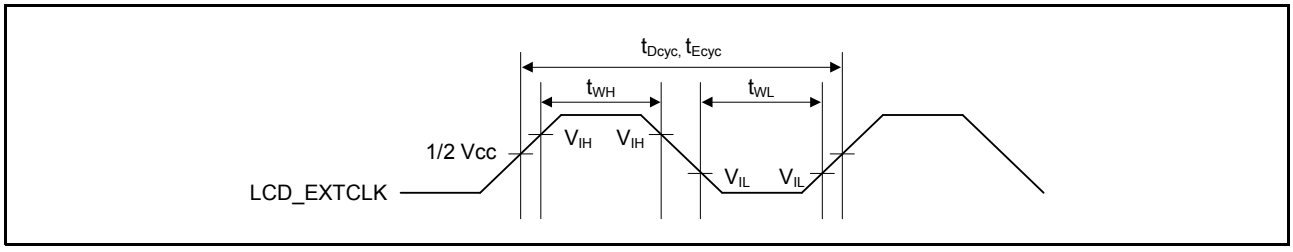


Figure 2.76 LCD_EXTCLK clock input timing

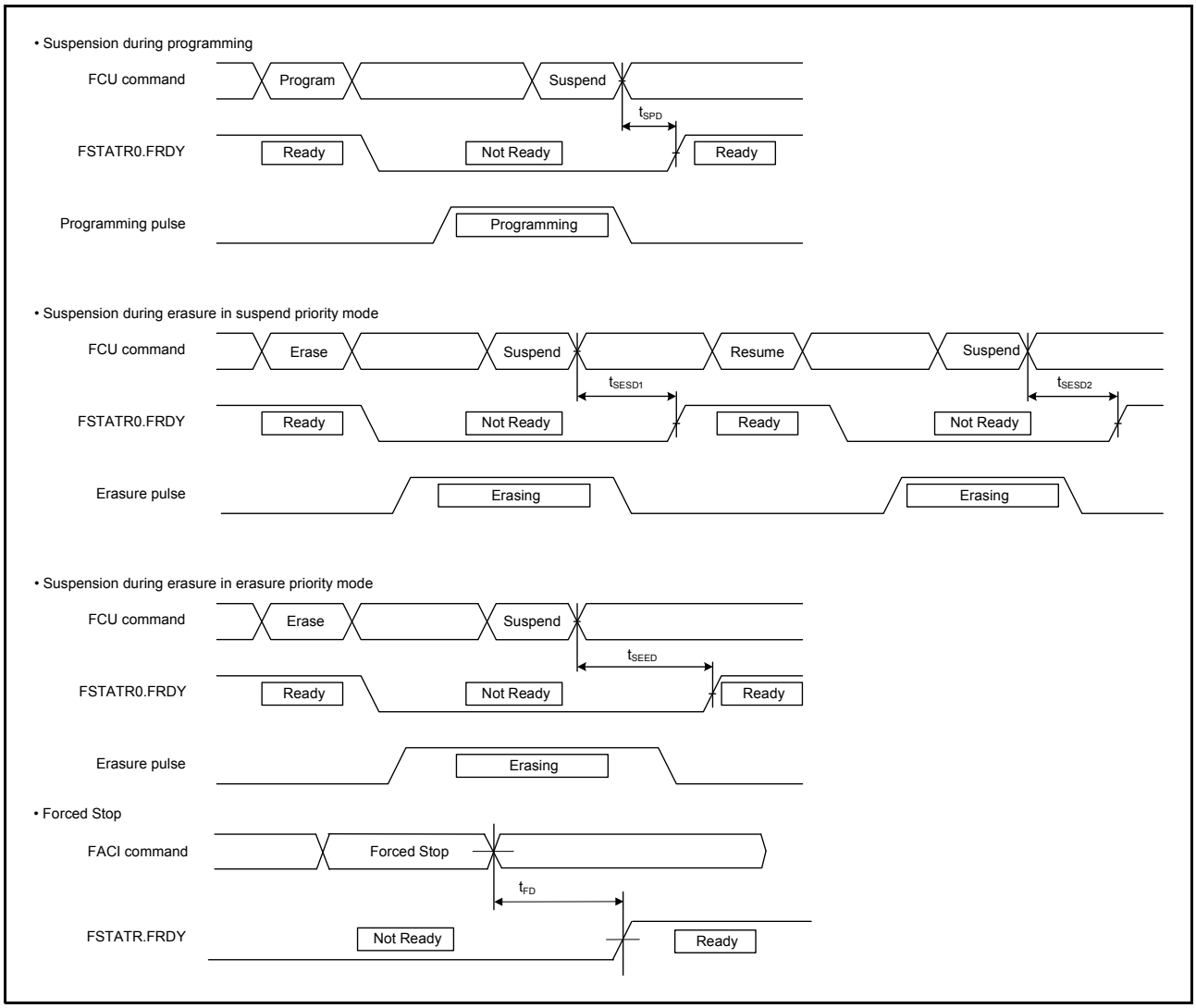


Figure 2.98 Suspension and forced stop timing for flash memory programming and erasure

2.14.2 Data Flash Memory Characteristics

Table 2.54 Data flash memory characteristics (1 of 2)
Conditions: Program or erase: FCLK = 4 to 60 MHz
Read: FCLK ≤ 60 MHz

Item		Symbol	FCLK = 4 MHz			20 MHz ≤ FCLK ≤ 60 MHz			Unit	Test conditions
			Min	Typ	Max	Min	Typ	Max		
Programming time	4-byte	t_{DP4}	-	0.46	3.8	-	0.21	1.7	ms	
	8-byte	t_{DP8}	-	0.48	4.0	-	0.22	1.8		
	16-byte	t_{DP16}	-	0.53	4.5	-	0.24	2.0		
Erasure time	64-byte	t_{DE64}	-	4.03	18	-	2.24	10	ms	
	128-byte	t_{DE128}	-	6.2	27	-	3.4	15		
	256-byte	t_{DE256}	-	11.6	50	-	6.4	28		
Blank check time	4-byte	t_{DBC4}	-	-	84	-	-	30	µs	
Reprogramming/erasure cycle*1		N_{DPEC}	125000 *2	-	-	125000 *2	-	-	-	

Table 2.54 Data flash memory characteristics (2 of 2)
Conditions: Program or erase: FCLK = 4 to 60 MHz
Read: FCLK ≤ 60 MHz

Item		Symbol	FCLK = 4 MHz			20 MHz ≤ FCLK ≤ 60 MHz			Unit	Test conditions
			Min	Typ	Max	Min	Typ	Max		
Suspend delay during programming	4-byte	t_{DSPD}	-	-	264	-	-	120	µs	
	8-byte		-	-	264	-	-	120		
	16-byte		-	-	264	-	-	120		
First suspend delay during erasure in suspend priority mode	64-byte	t_{DSESD1}	-	-	216	-	-	120	µs	
	128-byte		-	-	216	-	-	120		
	256-byte		-	-	216	-	-	120		
Second suspend delay during erasure in suspend priority mode	64-byte	t_{DSESD2}	-	-	300	-	-	300	µs	
	128-byte		-	-	390	-	-	390		
	256-byte		-	-	570	-	-	570		
Suspend delay during erasing in erasure priority mode	64-byte	t_{DSEED}	-	-	300	-	-	300	µs	
	128-byte		-	-	390	-	-	390		
	256-byte		-	-	570	-	-	570		
Forced stop command		t_{FD}	-	-	32	-	-	20	µs	
Data hold time*3		t_{DRP}	10*3,*4	-	-	10*3,*4	-	-	Year	
			30*3,*4	-	-	30*3,*4	-	-		Ta = +85°C

Note 1. The reprogram/erase cycle is the number of erasures for each block. When the reprogram/erase cycle is n times (n = 125,000), erasing can be performed n times for each block. For example, when 4-byte programming is performed 16 times for different addresses in 64-byte blocks, and then the entire block is erased, the reprogram/erase cycle is counted as one. However, programming the same address several times as one erasure is not enabled. (Overwriting is prohibited.)
Note 2. This is the minimum number of times to guarantee all the characteristics after reprogramming. The guaranteed range is from 1 to the minimum value.
Note 3. This indicates the minimum value of the characteristic when reprogramming is performed within the specified range.
Note 4. This result is obtained from reliability testing.

2.15 Boundary Scan

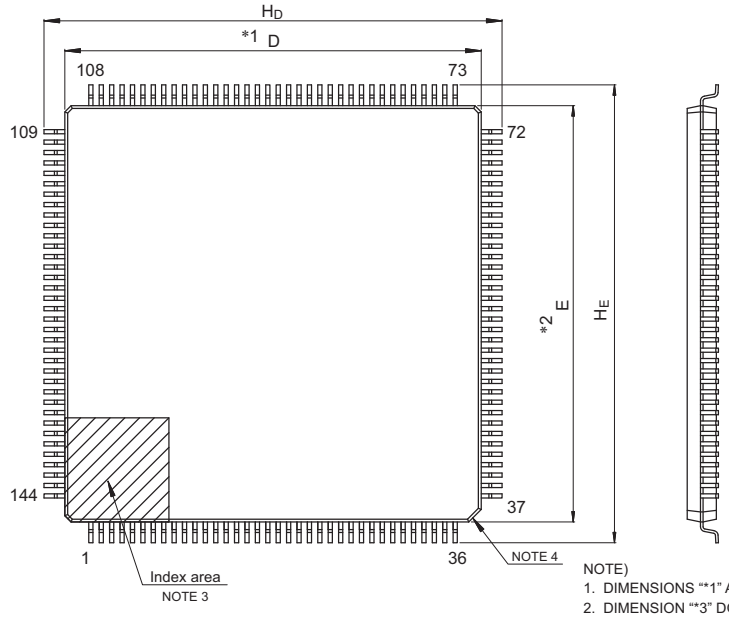
Table 2.55 Boundary scan characteristics

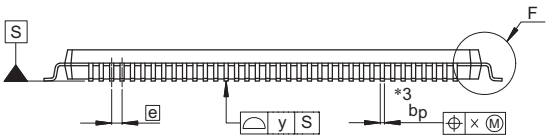
Item	Symbol	Min	Typ	Max	Unit	Test conditions
TCK clock cycle time	t_{TCKcyc}	100	-	-	ns	Figure 2.99
TCK clock high pulse width	t_{TCKH}	45	-	-	ns	
TCK clock low pulse width	t_{TCKL}	45	-	-	ns	
TCK clock rise time	t_{TCKr}	-	-	5	ns	
TCK clock fall time	t_{TCKf}	-	-	5	ns	
TMS setup time	t_{TMSS}	20	-	-	ns	Figure 2.100
TMS hold time	t_{TMSH}	20	-	-	ns	
TDI setup time	t_{TDIS}	20	-	-	ns	
TDI hold time	t_{TDIH}	20	-	-	ns	
TDO data delay	t_{TDOD}	-	-	40	ns	
Boundary scan circuit startup time*1	T_{BSSTUP}	t_{RESWP}	-	-	-	Figure 2.101

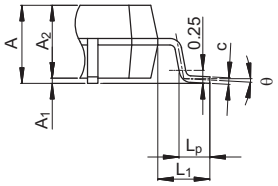
Note 1. Boundary scan does not function until the power-on reset becomes negative.

JEITA Package Code	RENESAS Code	Previous Code	MASS (Typ) [g]
P-LFQFP144-20x20-0.50	PLQP0144KA-B	—	1.2

Unit: mm







Detail F

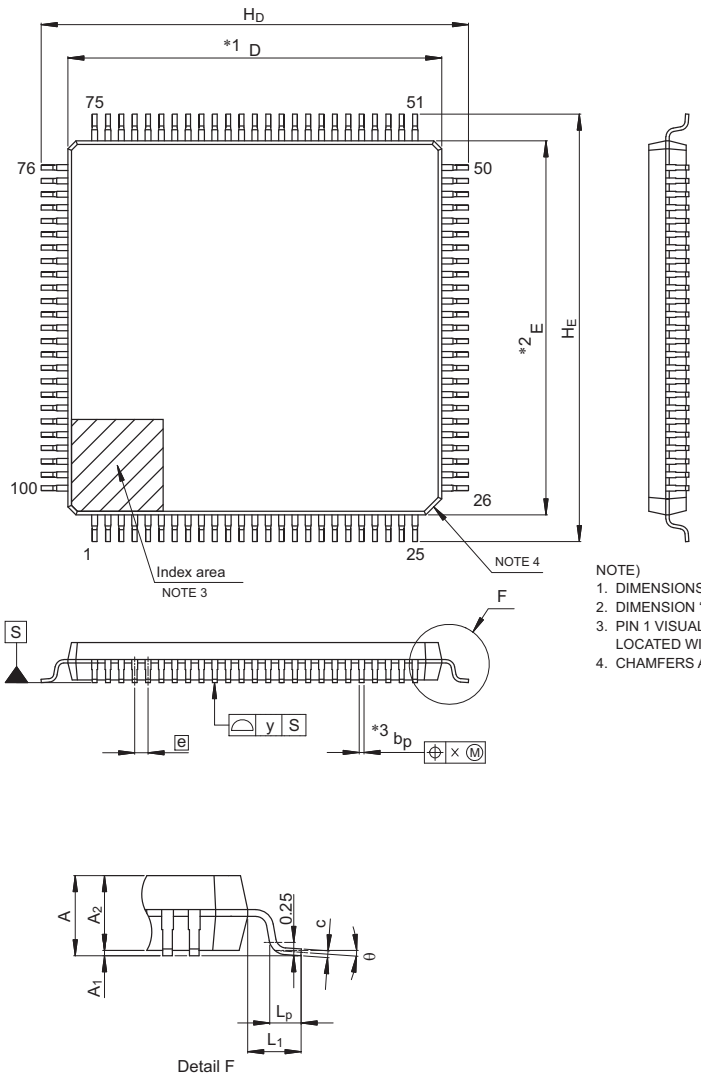
NOTE)
1. DIMENSIONS "*1" AND "*2" DO NOT INCLUDE MOLD FLASH.
2. DIMENSION "*3" DOES NOT INCLUDE TRIM OFFSET.
3. PIN 1 VISUAL INDEX FEATURE MAY VARY, BUT MUST BE LOCATED WITHIN THE HATCHED AREA.
4. CHAMFERS AT CORNERS ARE OPTIONAL, SIZE MAY VARY.

Reference Symbol	Dimensions in millimeters		
	Min	Nom	Max
D	19.9	20.0	20.1
E	19.9	20.0	20.1
A_2	—	1.4	—
H_D	21.8	22.0	22.2
H_E	21.8	22.0	22.2
A	—	—	1.7
A_1	0.05	—	0.15
b_p	0.17	0.20	0.27
c	0.09	—	0.20
θ	0°	3.5°	8°
e	—	0.5	—
x	—	—	0.08
y	—	—	0.08
L_p	0.45	0.6	0.75
L_1	—	1.0	—

Figure 1.4 144-pin LQFP

JEITA Package Code	RENESAS Code	Previous Code	MASS (Typ) [g]
P-LFQFP100-14x14-0.50	PLQP0100KB-B	—	0.6

Unit: mm



NOTE)
1. DIMENSIONS "*1" AND "*2" DO NOT INCLUDE MOLD FLASH.
2. DIMENSION "*3" DOES NOT INCLUDE TRIM OFFSET.
3. PIN 1 VISUAL INDEX FEATURE MAY VARY, BUT MUST BE LOCATED WITHIN THE HATCHED AREA.
4. CHAMFERS AT CORNERS ARE OPTIONAL, SIZE MAY VARY.

Reference Symbol	Dimensions in millimeters		
	Min	Nom	Max
D	13.9	14.0	14.1
E	13.9	14.0	14.1
A_2	—	1.4	—
H_D	15.8	16.0	16.2
H_E	15.8	16.0	16.2
A	—	—	1.7
A_1	0.05	—	0.15
b_p	0.15	0.20	0.27
c	0.09	—	0.20
θ	0°	3.5°	8°
e	—	0.5	—
x	—	—	0.08
y	—	—	0.08
L_p	0.45	0.6	0.75
L_1	—	1.0	—

Figure 1.5 100-pin LQFP

Renesas Synergy™ Platform
S5D9 Microcontroller

Renesas Electronics Corporation

R01DS0303EU0100